



<b>Title of Change:</b>	SOIC-8 Insourcing to ON Semiconductor Philippines (OSPI) Factory from HANA (Thailand) - Phase 1																
<b>Proposed first ship date:</b>	23 June 2018																
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Scott.Brow@onsemi.com>																
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office																
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Kyungwon.Kang@onsemi.com>																
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.																
<b>Change Part Identification:</b>	Product marked with date code 1810 or later may be built from current factory or from OSPI Factory. The trace code marking on Line 2 is of the form ALYW where A = Assembly Location, L = Wafer Lot ID and YW is a 2-digit date code. Product marked with "P" as the assembly location will be from OSPI. Additionally on the label of the box and reel, the ASSY LOC: PO will also indicate product assembled in OSPI. Please see sample label on Page 2 at the following URL <a href="http://www.onsemi.com/pub/Collateral/LABELRM-D.PDF">http://www.onsemi.com/pub/Collateral/LABELRM-D.PDF</a> to see the location of the ASSY LOC.																
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____																
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____																
<b>Sites Affected:</b>	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: HANA, Thailand															
<b>Description and Purpose:</b>																	
<p>ON Semiconductor would like to inform its customers of the qualification of ON Semiconductor Philippines (OSPI) for the assembly and test of a II of the SOIC-8 products listed in this Final Product Change Notification (FPCN). This is a capacity expansion, and at the end of the FPCN approval cycle, these products may be dual sourced from either HANA, Thailand or from OSPI.</p> <p>For Test, consigned testers and handlers as HANA have been transferred to OSPI to support the testing of products. The same load boards, test programs and other necessary hardware used in HANA, will be used to test the products listed.</p> <p>For assembly, BOM changes associated with this FPCN are shown here:</p>																	
<table border="1"> <thead> <tr> <th>Material to be changed</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Leadframe</td> <td>Cu NiPdAu Plating</td> <td>Cu NiPdAu Plating (no change)</td> </tr> <tr> <td>Mold Compound</td> <td>Hitachi CEL8240HF10LYR or KCC KTMC2036SA</td> <td>Sumitomo G600</td> </tr> <tr> <td>Die Attach</td> <td>Henkel QMI 519 or Epoxy,8351C</td> <td>Henkel ABP-8062T</td> </tr> <tr> <td>Wire Size and material</td> <td>1.0mil/1.3mil Au</td> <td>1.0mil/1.3mil Au (no change)</td> </tr> </tbody> </table>			Material to be changed	Before Change Description	After Change Description	Leadframe	Cu NiPdAu Plating	Cu NiPdAu Plating (no change)	Mold Compound	Hitachi CEL8240HF10LYR or KCC KTMC2036SA	Sumitomo G600	Die Attach	Henkel QMI 519 or Epoxy,8351C	Henkel ABP-8062T	Wire Size and material	1.0mil/1.3mil Au	1.0mil/1.3mil Au (no change)
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Additionally, this FPCN serves to notify customers of a change in the marking for all products listed for **BOTH** sites, HANA and OSPI. The new marking will be of the form:



Line 1 is the Product Identification (see table for new Product IDs)

Line 2 is the Trace code with the following nomenclature: A = Assy Location, L = Wafer Lot ID, YW = 2 digit date code. The X at the end of the line is a wrap character if additional identification is needed from Line 1.

HANA: A = H

OSPI: A = P

OPN	Line 1 Marking
FAN3121CMX	3121C
FAN3121TMX	3121T
FAN3122CMX	3122C
FAN3122TMX	3122T
FAN3213TMX	3213T
FAN3214TMX	3214T
FAN3216TMX	3216T
FAN3217TMX	3217T
FAN3223CMX	3223C
FAN3223TMX	3223T
FAN3224CMX	3224C
FAN3224TMX	3224T
FAN3225CMX	3225C
FAN3225TMX	3225T
FAN3226CMX	3226C
FAN3226TMX	3226T
FAN3227CMX	3227C
FAN3227TMX	3227T
FAN3229CMX	3229C

OPN	Line 1 Marking
FAN3229TMX	3229T
FAN3268TMX	3268T
FAN73611MX	73611
FAN7361MX	7361
FAN7362MX	7362
FAN73711MX	73711
FAN7371MX	7371
FAN7380MX	7380
FAN7380MX_OP	7380OP
FAN7382MX	7382
FAN73832MX	73832
FAN73833MX	73833
FAN7387MX	7387
FAN73901MX	73901
FAN7390MX	7390
FAN73932MX	73932
FAN7527BMX	7527B
FAN7711MX	7711
FAN7842MX	7842MX



## Reliability Data Summary:

QV DEVICE NAME FAN7380MXRMS K43324, O44678PACKAGE SOIC 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 80 % max rated Vcc	1008 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/80
THB	JESD22-A101C	85°C, 85% RH, bias	1008 hrs	0/80
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	-	0/320
SAT	JEDEC STD 035	Pre and Post MSL 1	-	0/25
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 10 sec	-	0/15
PD	JESD22-B100	Per POD, case 751EB	-	0/30
CDPA	MILSTD750 Method 2037	Wire Pull after TC500 cycles	-	0/5

QV DEVICE NAME: FAN3121CMXRMS W43327, O44740PACKAGE SOIC 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 80 % max rated Vcc	1008 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/80
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/80
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	-	0/320
SAT	JEDEC STD 035	Pre and Post MSL 1	-	0/25
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 10 sec	-	0/15
PD	JESD22-B100	Per POD, case 751EB	-	0/30
CDPA	MILSTD750 Method 2037	Wire Pull after TC500 cycles	-	0/5



QV DEVICE NAME: FAN7527BMX  
 RMS K43325, O44719  
 PACKAGE SOIC 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 80 % max rated Vcc	1008 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/80
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/80
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	192 hrs	0/80
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	-	0/320
SAT	JEDEC STD 035	Pre and Post MSL 1	-	0/25
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 10 sec	-	0/15
PD	JESD22-B100	Per POD, case 751EB	-	0/30
CDPA	MILSTD750 Method 2037	Wire Pull after TC500 cycles	-	0/5

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted by this change. Electrical comparison reports are available upon request

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
FAN3121CMX	FAN3121CMX
FAN3121TMX	FAN3121CMX
FAN3122CMX	FAN3121CMX
FAN3122TMX	FAN3121CMX
FAN3213TMX	FAN3121CMX
FAN3214TMX	FAN3121CMX
FAN3216TMX	FAN3121CMX
FAN3217TMX	FAN3121CMX
FAN3223CMX	FAN3121CMX
FAN3223TMX	FAN3121CMX
FAN3224CMX	FAN3121CMX
FAN3224TMX	FAN3121CMX
FAN3225CMX	FAN3121CMX



FAN3225TMX	FAN3121CMX
FAN3226CMX	FAN3121CMX
FAN3226TMX	FAN3121CMX
FAN3227CMX	FAN3121CMX
FAN3227TMX	FAN3121CMX
FAN3229CMX	FAN3121CMX
FAN3229TMX	FAN3121CMX
FAN3268TMX	FAN3121CMX
FAN73611MX	FAN7380MX
FAN7361MX	FAN7380MX
FAN7362MX	FAN7380MX
FAN73711MX	FAN7380MX
FAN7371MX	FAN7380MX
FAN7380MX	FAN7380MX
FAN7380MX_OP	FAN7380MX
FAN7382MX	FAN7380MX
FAN73832MX	FAN7380MX
FAN73833MX	FAN7380MX
FAN7387MX	FAN7380MX
FAN73901MX	FAN7380MX
FAN7390MX	FAN7380MX
FAN73932MX	FAN7380MX
FAN7527BMX	FAN7527BMX
FAN7711MX	FAN7380MX
FAN7842MX	FAN7380MX

**Appendix A: Changed Products**

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Product	Customer Part Number	Qualification Vehicle
FAN3121CMX		FAN3121CMX
FAN3121TMX		FAN3121CMX
FAN3122CMX		FAN3121CMX
FAN3122TMX		FAN3121CMX
FAN3213TMX		FAN3121CMX
FAN3214TMX		FAN3121CMX
FAN3216TMX		FAN3121CMX
FAN3217TMX		FAN3121CMX
FAN3223CMX		FAN3121CMX
FAN3223TMX		FAN3121CMX
FAN3224CMX		FAN3121CMX
FAN3224TMX		FAN3121CMX
FAN3225CMX		FAN3121CMX
FAN3225TMX		FAN3121CMX
FAN3226CMX		FAN3121CMX
FAN3226TMX		FAN3121CMX
FAN3227CMX		FAN3121CMX
FAN3227TMX		FAN3121CMX
FAN3229CMX		FAN3121CMX
FAN3229TMX		FAN3121CMX
FAN3268TMX		FAN3121CMX
FAN73611MX		FAN7380MX
FAN7361MX		FAN7380MX
FAN7362MX		FAN7380MX
FAN73711MX		FAN7380MX
FAN7371MX		FAN7380MX
FAN7380MX		FAN7380MX
FAN7380MX_OP		FAN7380MX
FAN7382MX		FAN7380MX
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FAN7387MX		FAN7380MX
FAN73901MX		FAN7380MX
FAN7390MX		FAN7380MX
FAN73932MX		FAN7380MX
FAN7527BMX		FAN7527BMX
FAN7711MX		FAN7380MX
FAN7842MX		FAN7380MX